



Product Change Notification

Change Notification #: 118094 - 00
Change Title: Select Intel® SSD 660p Series,
 PCN 118094-00, Label,
 Label Updates
Date of Publication: February 17, 2021

Key Characteristics of the Change:
 Label

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	March 19, 2021
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Description of Change to the Customer:

The Intel® SSD 660p Series SKUs listed in the Products Affected Table below will have the following label change.

- Update packaging labels with UKCA logo as shown below.

MOQ100 UKCA logo sticker



MOQ1 Pizzabox label

Current	New
<p>MM #: XXXXXX Pb-free 2LI</p> <p>QTY: 1</p> <p>SN: VSPPYWWDXXXXNNNFGN MADE IN CHINA WITH PARTIAL FOREIGN CONTENT</p> <p>PACKED BY: XXXXXX</p> <p>SSDXXXXXXXXXX</p> <p>CARTON #: XXXXXXXXXXXX 8 89296 11254 9</p> <p>BATCH #: XXXXXXXXXXXX</p> <p>VERSION #: XXXXXX-XXX</p> <p>PACK DATE: XX XXX XX</p> <p>Model: XXXXXXXXXXXXX</p>	<p>MM #: XXXXXX Pb-free 2LI</p> <p>QTY: 1</p> <p>SN: VSPPYWWDXXXXNNNFGN MADE IN XXXXX WITH PARTIAL FOREIGN CONTENT</p> <p>PACKED BY: XXXXXX</p> <p>SSDXXXXXXXXXX</p> <p>CARTON #: XXXXXXXXXXXX 8 89296 11254 9</p> <p>BATCH #: XXXXXXXXXXXX</p> <p>VERSION #: XXXXXX-XXX</p> <p>PACK DATE: XX XXX XX</p> <p>Model: XXXXXXXXXXXXX</p> <p>UK CA Intel Corporation (UK) Ltd., Attn: Corp Quality, Pipers Way, Swindon, Wiltshire SN3 1RJ, UK</p>

Customer Impact of Change and Recommended Action:

There is no change to the form, fit, or function of the product. The change is only to the labels used in packaging.

Customers should be aware of the changes to the label and take appropriate actions to accommodate the changes and avoid impact to their process.

Milestone dates are estimates and subject to change based on business and operational conditions.

Please contact your local Intel Field Sales Rep if you have any further questions about these changes.

Products Affected / Intel Ordering Codes:

Marketing Name	Product Code	MM#
Intel® SSD 660p Series (2.0TB, M.2 80mm PCIe 3.0 x4, 3D2, QLC) Generic Single Pack	SSDPEKNW020T801	976804
Intel® SSD 660p Series (2.0TB, M.2 80mm PCIe 3.0 x4, 3D2, QLC) Generic Single Pack	SSDPEKNW512G8AS	999M0M
Intel® SSD 660p Series (512GB, M.2 80mm PCIe 3.0 x4, 3D2, QLC) Generic 100 Pack	SSDPEKNW010T8AS	999M0V
Intel® SSD 660p Series (1.0TB, M.2 80mm PCIe 3.0 x4, 3D2, QLC) Generic 100 Pack	SSDPEKNW512G8AU	999M5F
Intel® SSD 660p Series (512GB, M.2 80mm PCIe 3.0 x4, 3D2, QLC) Generic Single Pack	SSDPEKNW010T8AU	999M5H

PCN Revision History:

Date of Revision:

February 17, 2021

Revision Number:

00

Reason:

Originally Published PCN



Product Change Notification

118094 - 00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

Americas Contact: asmo.pcn@intel.com

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